

Title (en)

Wood chips drying plant for drying wood chips and method for drying wood chips

Title (de)

Holzspan Trocknungsanlage zum Trocknen von Holzspänen und zugehöriges Verfahren zum Trocknen von Holzspänen

Title (fr)

Installation de séchage de copeaux de bois destinée à sécher des copeaux de bois et procédé correspondant destiné à sécher des copeaux de bois

Publication

**EP 2230477 B1 20141231 (DE)**

Application

**EP 09003440 A 20090310**

Priority

EP 09003440 A 20090310

Abstract (en)

[origin: EP2230477A1] The chip drying system (10) has a drier (16) for drying a wood chip (18). A recirculation apparatus (56) includes an exhaust vapor heater (42) and recalculates exhaust vapors (34) into the drier. The exhaust vapor heater is provided with a regenerative and/or catalytic heat exchanger, which is arranged downstream behind the drier. The regenerative and/or catalytic heat exchanger heats up the exhaust vapors to a temperature, which is high enough to oxidize the majority of particles present in the exhaust vapors. Independent claims are also included for the following: (1) a method for drying a wood chip (2) a method for producing a derived timber plate.

IPC 8 full level

**F26B 23/02** (2006.01)

CPC (source: EP KR US)

**F26B 3/00** (2013.01 - KR); **F26B 3/04** (2013.01 - KR); **F26B 21/002** (2013.01 - KR); **F26B 21/02** (2013.01 - KR); **F26B 23/02** (2013.01 - KR); **F26B 23/022** (2013.01 - EP KR US); **F26B 23/024** (2013.01 - EP KR US); **F26B 25/06** (2013.01 - KR); **F26B 2210/16** (2013.01 - EP KR US); **Y10T 428/253** (2015.01 - EP US)

Cited by

CN103712429A; DE102015108742A1; DE102015108742B4; WO202223075A1

Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO SE SI SK TR

DOCDB simple family (publication)

**EP 2230477 A1 20100922; EP 2230477 B1 20141231**; AU 2010223604 A1 20110908; AU 2010223604 B2 20141218; BR PI1009439 A2 20160301; CA 2753123 A1 20100916; CA 2753123 C 20161101; CN 102348949 A 20120208; CN 102348949 B 20140402; ES 2532627 T3 20150330; HU E024574 T2 20160229; JP 2012519828 A 20120830; JP 5734879 B2 20150617; KR 101671045 B1 20161031; KR 101738588 B1 20170522; KR 20110126163 A 20111122; KR 20160105536 A 20160906; MX 2011008847 A 20110929; PL 2230477 T3 20150529; PT 2230477 E 20150304; RU 2011140939 A 20130420; RU 2534197 C2 20141127; SI 2230477 T1 20150430; UA 106746 C2 20141010; US 2011305897 A1 20111215; US 8832959 B2 20140916; WO 2010102736 A1 20100916; ZA 201106123 B 20121031

DOCDB simple family (application)

**EP 09003440 A 20090310**; AU 2010223604 A 20100301; BR PI1009439 A 20100301; CA 2753123 A 20100301; CN 201080011606 A 20100301; EP 2010001245 W 20100301; ES 09003440 T 20090310; HU E09003440 A 20090310; JP 2011553322 A 20100301; KR 20117023539 A 20100301; KR 20167023267 A 20100301; MX 2011008847 A 20100301; PL 09003440 T 20090310; PT 09003440 T 20090310; RU 2011140939 A 20100301; SI 200931145 T 20090310; UA A201111855 A 20100301; US 201013202301 A 20100301; ZA 201106123 A 20110819